

Foreword



It is my pleasure to introduce Professor Bruce C. Kim as our newest Associate Editor. Dr. Kim earned his Bachelor's of Science in Electrical Engineering from the University of California at Irvine in 1981, his Masters of Science in Electrical Engineering from the University of Arizona in 1985, and his Ph.D. in Electrical Engineering from the Georgia Institute of Technology in 1996. Since that time, he has worked for a number of universities including Michigan State and Arizona State while focusing his research and teaching efforts on Microelectronics and

Electronic Packaging. Prior to his academic career, he also held engineering positions at Hughes Aircraft Company and the Allied Signal Company (Honeywell). Since 2005, he has worked for the University of Alabama at Tuscaloosa, where he currently serves as an Associate Professor in the Department of Electrical and Computer Engineering.

Professor Kim has a wealth of experience in electronic packaging and microelectronics. He has served in several editorial roles, published four book chapters, twenty-four journal papers, and seventy-seven conference publications in this area. He has also served as a key investigator on over nine million dollars of funded research. Therefore, his experience and depth of understanding in this field will be a great asset to this journal, and I look forward to working with him on coming issues.

The panel of associate editors that collaborate on this journal is the core group of people who evaluate perspective papers and ensure the timeliness and quality of the content that we publish in each issue. Without their sustained effort and expertise, this journal would not exist.

Fred D. Barlow III, Ph.D.
Editor-in-Chief